



29 Sept 2020

Singapore

Statement

UTAC Enters into Agreement to Purchase Singapore Wafer Bumping Related Assets from Powertech Technology (Singapore) Pte Ltd

UTAC Holdings Ltd. announced today that its affiliate (“UTAC” or “the Company”) has entered into an Asset Purchase Agreement (“APA”) to acquire the Singapore wafer bumping assets from Powertech Technology (Singapore) Pte Ltd (“PTI Singapore”). The transaction is expected to close on January 1, 2021.

As part of the APA, UTAC has entered into several ancillary agreements including a Transitional Services Agreement and License Agreement with Powertech Technology Inc. to help enable a seamless transition of the wafer bumping related operations to UTAC. In addition, as part of the acquisition of wafer bumping assets from PTI Singapore, UTAC expects to offer employment to all current employees of PTI Singapore’s bumping operations from January 1, 2021.

“We look forward to completing this transaction with PTI Singapore enabling advance 300mm wafer bumping capabilities and technology to remain on-island,” said Dr. John Nelson, Chief Executive Officer of UTAC. We also welcome the PTI Singapore wafer bumping employees to the UTAC family.



About UTAC Holdings Ltd

UTAC Holdings Ltd (UTAC) is a leading independent provider of assembly and test services for a broad range of semiconductor chips and we offer a full range of semiconductor assembly and test services in the following key product categories: analog, mixed-signal and logic, and memory. Our customers are primarily fabless companies, integrated device manufacturers and wafer foundries. UTAC is headquartered in Singapore, with production facilities located in Singapore, Thailand, China, Indonesia and Malaysia, in addition to its global sales network focused on five regions: United States, Japan, China, rest of Asia and Europe, with sales offices located in each of these regions.